



08-23-2002

Atty. Docket No.: 0630-1341P

Page 1 of 1



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To the Honorable Commissioner of Patents and Trademarks:  
Please record the attached original documents or copy thereof.

8.19.02

## 1. Name of conveying party(ies):

[FAMILY NAME (ALL CAPS), Given Name]

KIM, Yong Hwan

Additional name(s) of conveying party(ies) attached?

☐ YES ☒ NO

## 3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other:

Execution Date: May 20, 2002

## 2. Name and address of receiving party(ies)

Name: HYNIX SEMICONDUCTOR, INC.

Internal Address:

Street Address: San 136-1, Ami-Ri, Bubal-Eub

City: Ichon-Shi

State: Kyoungki-Do

ZIP:

Country: Korea

Postal Code:

Additional name(s) & address(es) attached? ☐ YES ☒ NO

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No(s).

10/153,801

B. Patent No.(s).

Additional numbers attached? ☐ YES ☒ NO

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: BIRCH, STEWART, KOLASCH &amp; BIRCH, LLP

Street Address: P.O. BOX 747

City: FALLS CHURCH State: VA ZIP: 22040-0747

Country: USA

## 6. Total No. of applications/patents involved: One (1)

## 7. Total fee (37 C.F.R. § 3.41): \$40.00

☒ Enclosed☒ Authorized to be charged to deposit account,  
if no fee attached.

## 8. Deposit account number: 02-2448

(Attach triplicate copy of this page  
if paying by deposit account)

DO NOT USE THIS SPACE

## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Joseph A. Kolasch, #22,463

Name of Person Signing/Reg. No.

Signature

August 19, 2002

Date

Total number of pages including cover sheet, attachments, and document: Seven (7)

JAK/cqc

(Rev. 02/11/02)

08/22/2002 AAHMD1 00000092 10153801

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PATENT  
REEL: 013207 FRAME: 0013

05-31-2002



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5/24/02

Atty. Docket No.: 0630-1341P

Page 1 of 1

## COVER SHEET

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## 4. Application number(s) or patent number(s):

10153801

If this document is being filed together with a new application, the execution date of the application is: May 20, 2002

## A. Patent Application No(s).

New

## B. Patent No.(s).

Additional numbers attached? ☐ YES ☒ NO

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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Joseph A. Kolasch, #22,463

Name of Person Signing/Reg. No.

Signature

May 24, 2002

Date

Total number of pages including cover sheet, attachments, and document: Three (3)

05/24/2002 11:11 00000002 10153801

02 FC:581

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JAK/cqc

(Rev. 02/11/02)

PATENT  
REEL: 013207 FRAME: 0014

**BIRCH, STEWART, KOLASCH & BIRCH, LLP**UNITED STATES PATENT RIGHTS, OR  
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS**ASSIGNMENT**Application No. NewFiled May 24, 2002Name(s)  
Inventor(s)WHEREAS, Yong Hwan KIM

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in

Title  
InventionCIRCUIT FOR GENERATING HIGH VOLTAGE

for which an application for Letters Patent of the United States of America has been executed by the undersigned (except in the case of a provisional application).

Date  
Filing of  
Applicationon May 20, 2002; andName  
AssigneeWHEREAS, HYNIX SEMICONDUCTOR, INC.Address  
Assigneeof San 136-1, Ami-Ri, Bubal-Eub, Ichon-Shi, Kyoungki-Do, Korea

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

☐ **IF BOX  
IS APPROPRIATE**☐ in any foreign countries.

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

<u>May 20, 2002</u> _____ _____ _____ _____ _____	Name of Inventor <u>Yong Hwan Kim</u> (signature) Yong Hwan KIM  Name of Inventor _____ (signature)  Name of Inventor _____ (signature)  Name of Inventor _____ (signature)  Name of Inventor _____ (signature)  Name of Inventor _____ (signature)
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